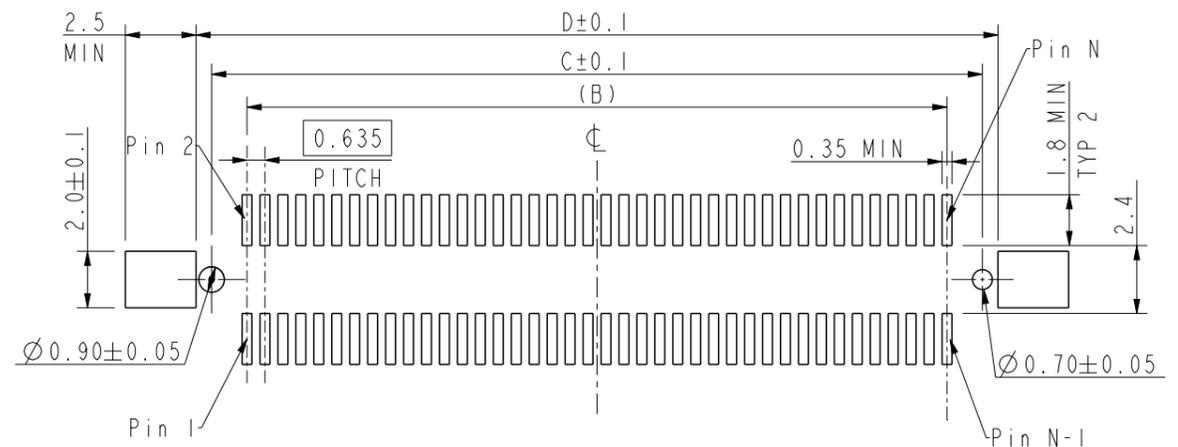
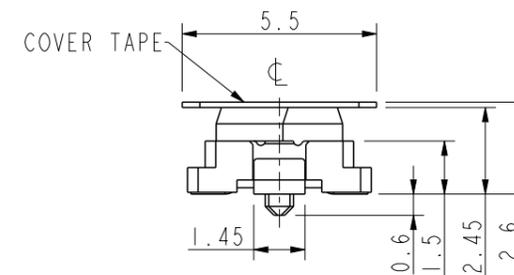
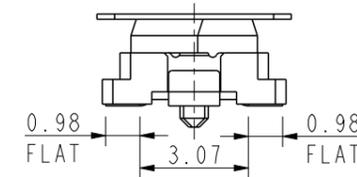
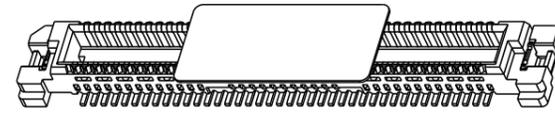
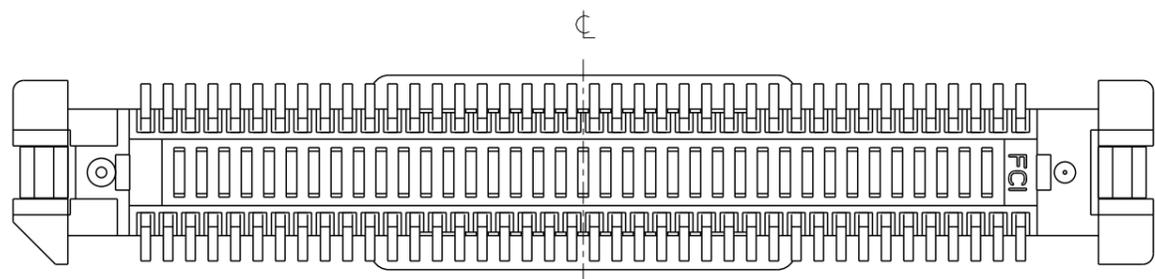
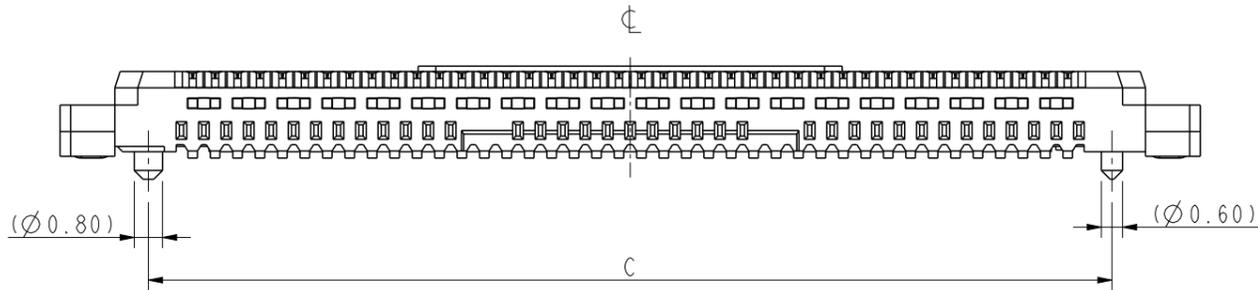
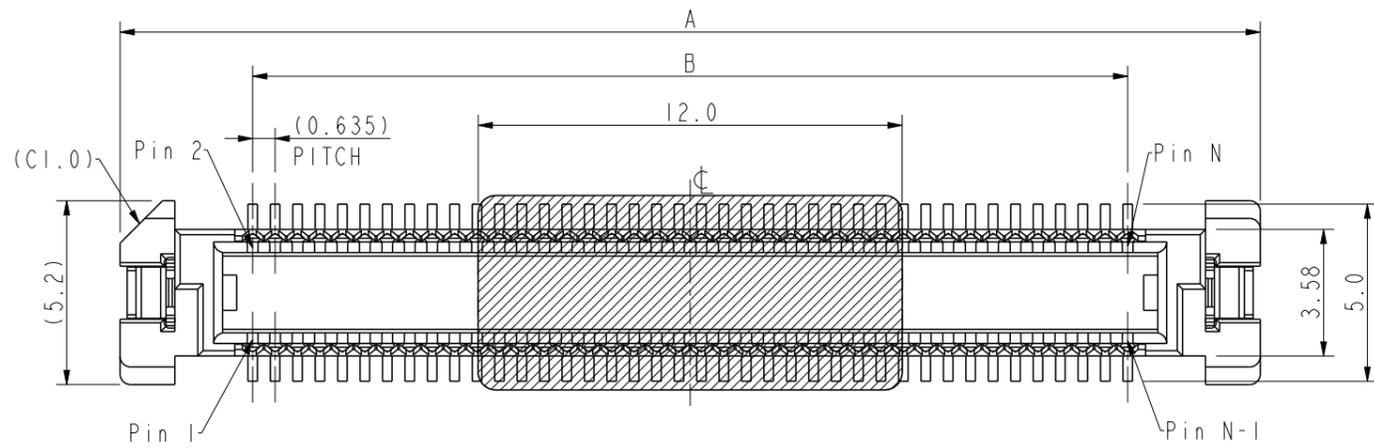


Part Number	POS	DIM "A"	DIM "B"	DIM "C"	DIM "D"
10169697-40000RLF	80	32.27	24.765	27.27	28.37
10169697-70000RLF	140	51.32	43.815	46.32	47.42



RECOMMENDED PCB PATTERN LAYOUT

NOTES:

1. MATERIAL:
 - 1.1 HOUSING: LCP, WHITE, UL94V-0
 - 1.2 TERMINAL AND HOLD DOWN: COPPER ALLOY.
 - 1.3 VACUUM TAPE: POLYIMIDE (PI)
2. PLATING:
 - 2.1 1.5µm MIN NI UNDER PLATING;
 - 2.2 0.05µm MIN AU ON SOLDER AREA;
 - 2.3 0.10µm MIN AU ON MATING AREA.
3. PRODUCTION SPECIFICATION GS-12-1709;
4. THIS HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 20 SECONDS IN A IR REFLOW SOLDERING APPLICATION;
5. THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008;
6. COPLANARITY AREA OF TERMINATION 0.1MM MAX.

spec ref	dr	Hao-Liang Sun	2022/11/03	projection	mm	size	A3	scale	5:1
tolerance std	eng	-	2022/11/03			ecn no	-	rel level	Preliminary
TOLERANCES UNLESS OTHERWISE SPECIFIED									
surface	linear	0.X	±0.25			dwg no	10169697	rev	1
		0.XX	±0.15						
		0.XXX	±0.05						
	angular	0°	±2°	amphenol-icc.com	cat. no.	Product - Customer Drw	sheet 1 of 1		